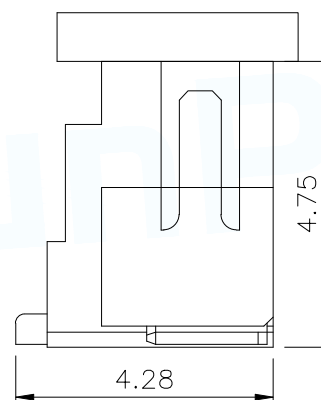
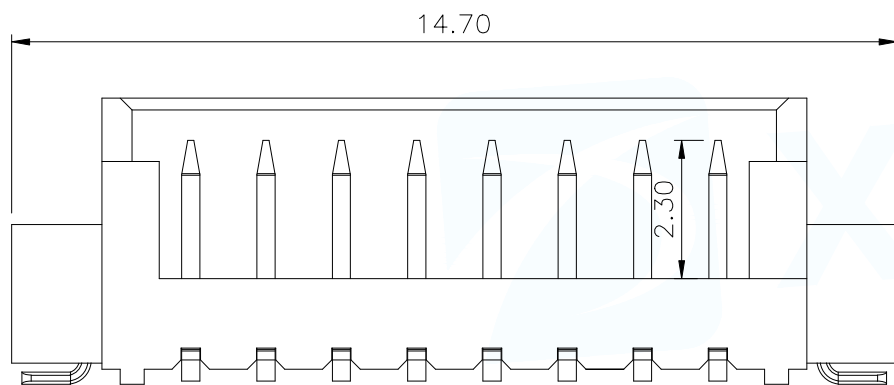
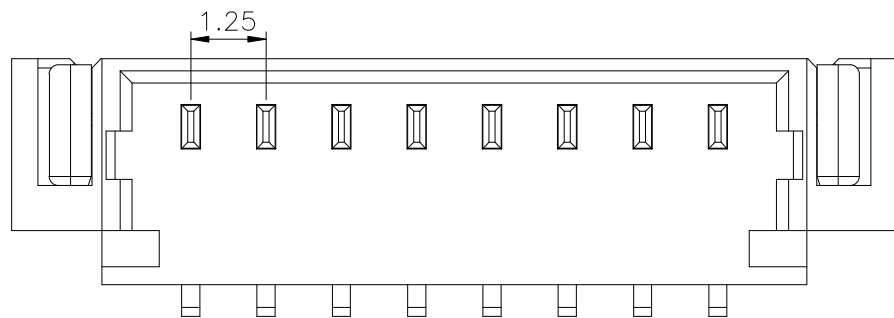


NOTES:

- 1.MATERIAL:
 - HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V_0
 - CONTACT: COPPER ALLOYS.
 - COVER: COPPER ALLOYS OR STEEL.
- 2.PLATING:
 - UNDERPLATE: NICKEL.

SPECIFICATIONS:

- Voltage Rating:125V AC DC
- Current Rating:1A AC,DC
- Withstanding voltage:500V AC 1/Minute
- Insulation Resistance:100MΩ Min
- Contact Resistance:20mΩ Max
- Temperatuer Range:-25℃ ~+ 85℃



MANUFACTURE DWG

东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,Ltd

UNLESS OTHERWISE SPECIFIED TOLERANCES



TITLE:
WAFER 1.25 立脚8P

DECIMALS:	ANGLES:
X.X:±0.35	X.X':±3°
X.XX:±0.25	X.XX:±2'
X.XXX:±0.15	

PAR	WAFER-125L-8P
DWN	
CHKD	
APVD	
SCALE1:1	UNIT:MM
SIZE:A4	SHEET:1F1
	REV:A

CUSTOMER COPY